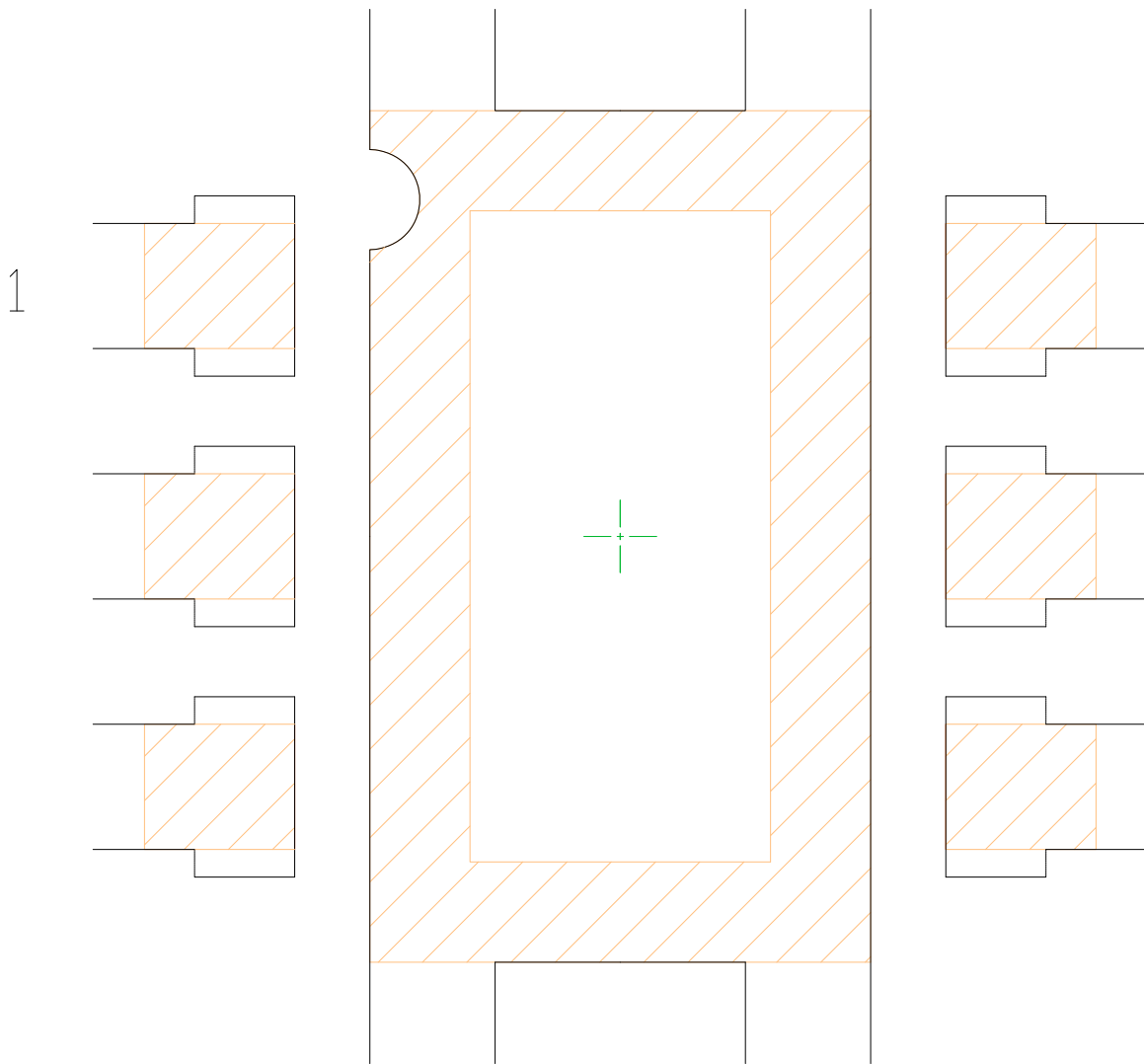



REVISIONS		
REV	DESCRIPTION	DATE
C	UPDATE PLATING SPEC	8-21-2017



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.00 x 1.70 mm	
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 0.80 x 1.45 mm	TITLE
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	DFN 6L 2x2 mm 0.50 PITCH BOND SHELL
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N:
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	235-00068
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	REV 00
DO NOT SCALE		FILE NAME 6L-DFN-2X2-50P-BD.DWG
		SHEET 1 OF 1